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Important! This is a music CD, created in real-life. Piano Complementario 1 Emilio Molina Pdf Download 2 . No items have been added yet! Related Collections. Image with no alt text. 3 file. 1 download. Piano Complementario 1 Emilio Molina Pdf Download 1 . No items have been added yet! Related Collections. Image with no alt text. The present invention relates to a protective film construction, which is formed by laminating a base, a releasing layer, an upper layer and an adhesive layer onto a protecting board to provide a protective film for protecting a circuit substrate. In the production of an assembly of a printed circuit board and components, it is often required to mount components on an electric circuit pattern of a printed circuit board. This mounting is usually performed by a solder reflow technique. Specifically, the mounting operation comprises steps of applying solder to an electrode of a component, pressing the component to the printed circuit board, then heating them at a temperature above 450.degree. C., thereby melting the solder to affix the component to the printed circuit board. Such an operation, however, has the following problems. The solder applied to the electrodes of the component runs down to the portion of the printed circuit board onto which the component is to be mounted, so that the portion comes to lack in electric continuity. Also, the solder tends to return to the surface of the component, so that the soldered portions are peeled off, causing a reduction in reliability of the component. Furthermore, the presence of the solder in the peripheral portions of the printed circuit board makes it difficult to evacuate the air, thereby increasing the temperature of the board. To solve these problems, it has been suggested to provide a solder resist layer which is adapted to prevent the solder from spreading on the portion of the printed circuit board onto which the component is to be mounted. This method, however, has another problem that the solder resist layer acts as an obstructing member to the amount of solder applied to the component electrodes and inhibits a good solder joint. Moreover, the solder resist layer tends to melt at the same time as the solder, thereby reducing the solder resist layer's ability to prevent the solder from spreading on the portion of the printed circuit board to which the component is to be mounted. The inventor has proposed a releasing type assembly of an electric circuit substrate and components, which is provided with a protector film having excellent heat-proofing, water-proofing and dust- f678ea9f9e